

Certificate of Compliance

DUNS		Document Date	URL for Additional Information
00-489-5751		Fri, Feb 21, 2014 06:44 PM	Fairchildsemi.com
Contact	Title	Phone	Email
David Lancaster	Product Ecology Manager	801.562.7455	david.lancaster@fairchildsemi.com

Material Declaration Processing Information

FSID	Material Declaration	Site Owner	Assembly Location	Package Weight(g)	MSL Rating
GBPC2510	GBPC_T	SUZHOU	SUBCONTRACTOR	18.1944400	Not Applicable
Terminal Finish	Base Alloy	Green Status	Reflow Cycles	Max Time at Temp	Peak Temp
Other	CU Alloy	This product is not considered GREEN as defined by Fairchild's Green Policy. Please use this link to access Fairchild's Green Product Definition. Fairchild's Green Policy	Not Applicable		

Homogenous Material Composition Declaration

Component	Material	Weight of Component(mg)	Substance	Weight (mg)	CAS	PPM in FSID
Aluminum Heat sink	Aluminum & its alloys	3345.0000	Aluminum	3345.0000	7429-90-5	183847
Case	Other Organic Materials	4075.0000	Phosphorus	81.5000	7723-14-0	4479
			Phenol resin	326.0000	9003-35-4	17918
			Epoxy Resin	815.0000	25008-38-6	44794
			Silica crystalline	2852.5000	14464-46-1	156779
			EPOXY	6971.2250	Carbon Black	55.7653
			Antimony Trioxide	223.0612	1309-64-4	12260
			Epoxy Resin	1394.1328	2389-87-0	76624
			Alicyclic anhydride	2510.0000	19438-60-9	137954
			Silica, vitreous	2788.2656	60676-86-0	153248
			GPP Dice	Ceramics / Glass	36.8890	Gold
			Nickel	0.2398	7440-02-0	13
			Glass	3.3938	65997-18-4	187
			Silicon	33.2001	7440-21-3	1825
			Marking Ink	Other Organic Materials	2.0000	2-Methyl-1-propanol
			Formaldehyde	0.0200	50-00-0	1
			1-Butanol	0.1000	71-36-3	5
			Hexahydrophthalic anhydride	0.1000	85-42-7	5
			Aluminum	0.5800	7429-90-5	32
			Triethyl Phosphate	0.5800	78-40-0	32
			Tributyl phosphate	0.6000	126-73-8	33
			Plating Layer	Aluminum & its alloys	1.9660	Nickel

Solder Paste	Other Nonferrous metals & alloys	20.0000	Silver	0.5000	7440-22-4	27
			Tin	1.0000	7440-31-5	55
			Lead	18.5000	7439-92-1	1017
Solder Wafer		85.3600	Silver	2.1340	7440-22-4	117
			Tin	4.2680	7440-31-5	235
			Lead	78.9580	7439-92-1	4340
Terminal (plating Cu)	Copper & its alloys	2516.0000	Phosphorus	1.0819	7723-14-0	59
			Iron	3.0192	7439-89-6	166
			Copper	2511.8989	7440-50-8	138059
Thin Copper		1141.0000	Phosphorus	0.2282	7723-14-0	13
			Iron	0.9128	7439-89-6	50
			Copper	1139.8590	7440-50-8	62649

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification.

Additionally, the following should be noted:

- This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product.
- CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) to 0.1% (1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01% (100 PPM) in homogeneous materials of electronic products.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU.

Exemptions as declared for the directive are: 7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

China RoHS

With the possible exception of lead, if applicable (refer to the RoHS Declaration statement above), this product and all homogeneous materials in the product comply with the China RoHS standard SJ/T 11363-2006.

REACH Compliance

European Union Regulation (EC) No 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) entered into force on June 1, 2007. Fairchild Semiconductor agrees with the purpose of REACH, which is to ensure a high level of protection of human health and the environment. Fairchild semiconductor is compliant with all applicable requirements of REACH and upon request will provide information regarding the chemical composition of our products.

Fairchild Semiconductor is neither a manufacturer nor importer of preparations into Europe and therefore the registration requirements of REACH do not apply to us. It is expected that any electronic materials manufacturer that uses preparations from Europe in their products will ensure compliance with REACH registration requirements.

Product (articles) manufacturers or importers into Europe are obligated under Article 33 of REACH to inform recipients of any articles that contain chemicals on the Substances of Very High Concern (SVHC) candidate list above a 0.1% concentration (by weight per article). Products manufactured and marketed by Fairchild Semiconductor do not contain substances on the REACH SVHC candidate list (as published by the ECHA on the following publication dates) in concentrations greater than 0.1% by weight per article:

October 28, 2008; January 13, 2010, March 30, 2010; June 18, 2010; December 15, 2010; June 20, 2011; December 19, 2011; June 18, 2012*; December 19, 2012; June 20, 2013.

Fairchild Semiconductor will continue to monitor the developments of REACH and is committed to meeting our responsibilities as an environmentally-responsible company. Please refer to the web site below for additional information regarding SVHC:

[ECHA European Chemical Agency](#)

* Diboron trioxide was added to REACH Annex XIV as a Substance of Very High Concern (SVHC) on June 18, 2012. Fairchild products in glass encapsulated packages may list Diboron trioxide as a constituent material in the glass encapsulation, in a concentration greater than 0.1%; REACH classifies; glass as a substance of unknown or variable composition, complex reaction products or biological matter (UVCB) containing the elements silica, calcium, sodium, potassium, magnesium and other cautions bonded together with oxygen. In glass, these elements are bonded into a non crystalline molecular structure with completely different properties than the starting material; Therefore Diboron trioxide is not present in the finished Fairchild product and does not require notification of the presents of a SVHC.

Joint Industry Guide (JIG) 101

With the exception of RoHS exemptions listed above (if applicable), this product does not contain any restricted substances listed in the Joint Industry Guide (JIG) 101 in concentrations greater than the threshold listed. The list of JIG substances may be viewed using this web link.

[Joint Industry Guide \(JIG\) 101](#)

The signature below is of the Company's designated personnel with delegated product ecology compliance responsibility and verifies that to the best of our knowledge the statements above are valid and accurate.

David Lancaster



Product Ecology Manager

Fairchild Semiconductor

3333 W 9000 S

West Jordan, UT 84088

Tel 1-801-562-7455

Email: david.lancaster@fairchildsemi.com



Environmental Declaration

The content of this document is based upon information collected from Fairchild Semiconductor's supply chain, manufacturing facilities and affiliates worldwide. Providing for limitations below, Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this page.

Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.